



ON THE UNITED STATES PATENT AND TRADEMARK OFFICE

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In re Patent Application of WANG et al.

S/N: 09/583,599

Filed: May 31, 2000

For: "Improved Acid Copper Electroplating Solutions"

Atty. Dkt. 99A209

Group No.: Not Yet Known

Examiner: Not Yet Known Leader R

Assistant Commissioner for Patents

Washington, DC 20231

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231, on JUNE 29, 2000.

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Betty Lee

Signature of person mailing

INFORMATION DISCLOSURE STATEMENT (37 CFR 1.97)

The Examiner's attention is directed to the documents identified on the attached Form PTO-1449, "Information Disclosure Statement by Applicant". A copy of each document is enclosed.

Please consider all the listed documents and list them on the cover sheet of any patents to issue from the subject application.

This Statement is filed within three months following the above identified application. In accordance with 37 CFR 1.97(b), no additional fee is due. As a precaution, the Commissioner is hereby authorized to charge to Deposit Account No. 02-2865 any fee required by this submission.

Very truly yours,

Philip H. Von Neida
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Attachments
Form PTO-1449
Cited References

PVN:bjl